



## Final Product Change Notification

201806035F01

**Issue Date:** 30-Jul-2018

**Effective Date:** 28-Oct-2018

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# QUALITY

### Management Summary

Cu Wire is being added as wirebond material option for LPC802M001JDH16 in TSSOP16 package at assembly site ASEN.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |  |   |   |

LPC802M001JDH16 Cu Wire Qualification for ASEN

### Description of Change

Copper wire has been qualified and will be added as a wirebond material. To support a robust wirebond process, the mold compound has also changed. After the effective date NXP will begin shipping product with copper wire.

See attached Self Qualification Report (SQR) for details of the affected part numbers, material changes and qualification test results.

### Reason for Change

Adding Copper wire is required to mitigate against raw material cost increases and for supply assurance. The mold compound change enables a robust Cu wirebond process

### Identification of Affected Products

Top side marking

Product revision is incremented. See marking details in attached SQR document.

## Product Availability

### Sample Information

Samples are available from 28-Jul-2018

The product version is Rev "1C". Samples with Cu wire can be ordered under the following part numbers: LPC802DH16/CP3365.

### Production

Planned first shipment 19-Oct-2018

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

Wire composition and mold compound are the only change to form. No Impact to fit or function. Reliability is equivalent or improved.

### Data Sheet Revision

No impact to existing datasheet

## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 29-Aug-2018.

## Remarks

Once the PCN expires, customers can receive either Au or Cu wire.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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### Affected Part Number

LPC802M001JDH16FP